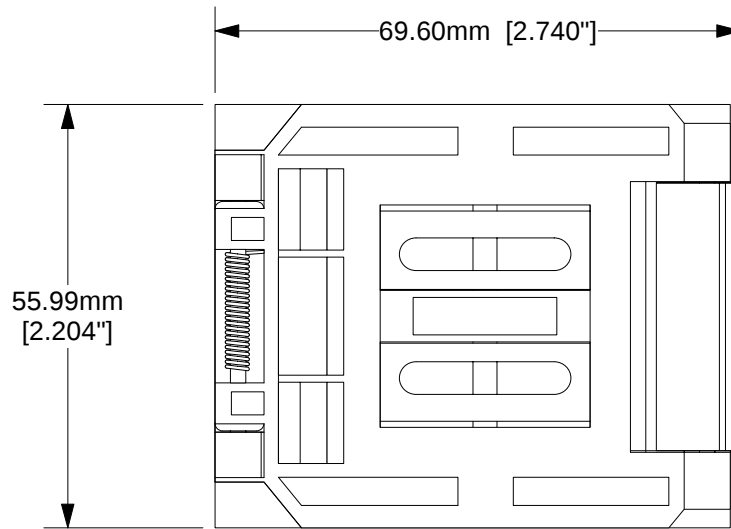
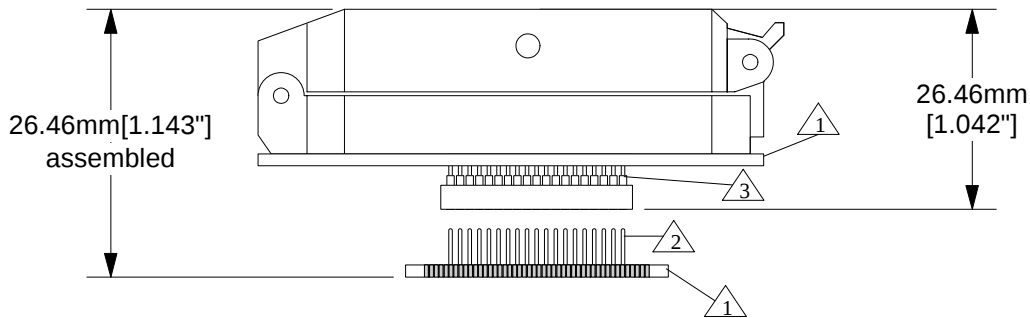
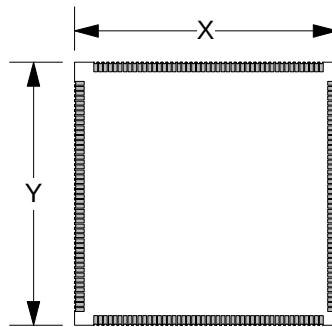




Top View



Side View



Footprint	Dim "X"	Dim "Y"
QFE184SA	35.2mm	35.2mm
QFE184SB	35.9mm	35.9mm

Bottom view; SMT base (only)

1 Substrate: 1.59mm $\pm$ 0.18mm [0.0625" $\pm$ 0.007"]
FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. SnPb plating.

2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.).

3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.). Contact material- BeCu; finish 0.25 μ m [10 μ "] Au over 2.54 μ m [100 μ "] Ni (min.).

Description: Carrier Adaptor

184 position (0.65mm pitch) QFP Zero Insertion Force socket to 184 position surface mountable QFP emulator foot. The 2 piece adaptor interconnects via gold plated (0.05" center) Mini-grid socket interface.

Tolerances: diameters $\pm$ 0.03mm [$\pm$ 0.001"], PCB perimeters $\pm$ 0.13mm [$\pm$ 0.005"], PCB thicknesses $\pm$ 0.18mm [$\pm$ 0.007"], pitches (from true position) $\pm$ 0.08mm [$\pm$ 0.003"], all other tolerances $\pm$ 0.13mm [$\pm$ 0.005"] unless stated otherwise.

CA-QFE184S(A,B)-L-Z-01 Drawing		Status: Released	Scale 4:3	Rev: A
 © 2000 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: W. Watson		Date: 5/26/00	
	File: CA-QFE184SA-L-Z-01 Dwg		Modified:	